

MOS FIELD EFFECT TRANSISTOR NP60N055KUG

SWITCHING N-CHANNEL POWER MOS FET

DESCRIPTION

The NP60N055KUG is N-channel MOS Field Effect
Transistor designed for high current switching applications.

ORDERING INFORMATION

PART NUMBER	PACKAGE
NP60N055KUG	TO-263 (MP-25ZK)

FEATURES

- Channel temperature 175 degree rating
- Super low on-state resistance

 $R_{DS(on)}$ = 9.4 m Ω MAX. (V_{GS} = 10 V, I_D = 30 A)

• Low Ciss: Ciss = 3700 pF TYP.

(TO-263)



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^{\circ}C$)

Drain to Source Voltage (VGS = 0 V)	VDSS	55	V
Gate to Source Voltage (V _{DS} = 0 V)	Vgss	±20	V
Drain Current (DC) (Tc = 25°C)	ID(DC)	±60	Α
Drain Current (pulse) Note1	D(pulse)	±240	Α
Total Power Dissipation (T _A = 25°C)	P _{T1}	1.8	W
Total Power Dissipation (Tc = 25°C)	P _{T2}	88	W
Channel Temperature	Tch	175	°C
Storage Temperature	T _{stg}	-55 to +175	°C
Repetitive Avalanche Current Note2	lar	27	Α
Repetitive Avalanche Energy Note2	Ear	73	mJ

Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1%

2. Tch < 150°C, VdD = 28 V, Rg = 25 Ω , Vgs = 20 \rightarrow 0 V

THERMAL RESISTANCE

Channel to Case Thermal Resistance Rth(ch-C) 1.70 °C/W Channel to Ambient Thermal Resistance Rth(ch-A) 83.3 °C/W

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ELECTRICAL CHARACTERISTICS (TA = 25°C)

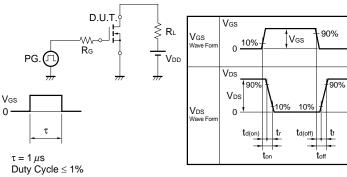
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 55 V, V _{GS} = 0 V			1	μΑ
Gate Leakage Current	Igss	V _{GS} = ±20 V, V _{DS} = 0 V			±100	nA
Gate to Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	2.0	3.0	4.0	V
Forward Transfer Admittance Note	y _{fs}	V _{DS} = 10 V, I _D = 30 A	11	22		S
Drain to Source On-state Resistance Note	RDS(on)	V _{GS} = 10 V, I _D = 30 A		7.4	9.4	mΩ
Input Capacitance	Ciss	V _{DS} = 25 V		3700	5600	pF
Output Capacitance	Coss	V _{GS} = 0 V		270	410	pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		160	290	pF
Turn-on Delay Time	t _{d(on)}	V _{DD} = 28 V, I _D = 30 A		30	66	ns
Rise Time	t r	V _{GS} = 10 V		44	110	ns
Turn-off Delay Time	td(off)	R _G = 0 Ω		79	160	ns
Fall Time	tr			8	20	ns
Total Gate Charge	Q _G	V _{DD} = 44 V		61	92	nC
Gate to Source Charge	Qgs	V _{GS} = 10 V		14		nC
Gate to Drain Charge	Q _{GD}	I _D = 60 A		20		nC
Body Diode Forward Voltage Note	V _F (S-D)	I _F = 60 A, V _{GS} = 0 V		0.94	1.5	V
Reverse Recovery Time	trr	I _F = 60 A, V _{GS} = 0 V		38		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		41		nC

Note Pulsed

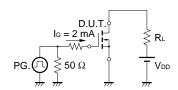
TEST CIRCUIT 1 AVALANCHE CAPABILITY

$V_{GS} = 20 \rightarrow 0 \text{ V}$ V_{DD} V_{DD}

TEST CIRCUIT 2 SWITCHING TIME



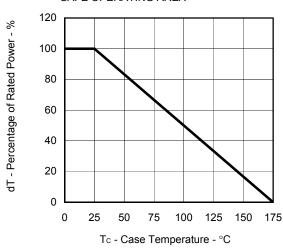
TEST CIRCUIT 3 GATE CHARGE



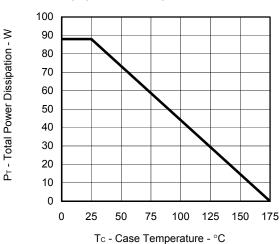
Starting Tch

TYPICAL CHARACTERISTICS (TA = 25°C)

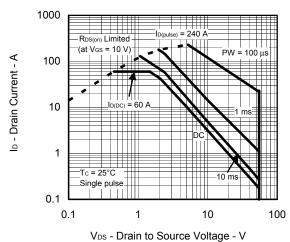
DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



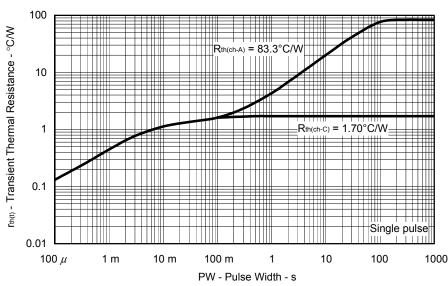
TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



FORWARD BIAS SAFE OPERATING AREA



TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

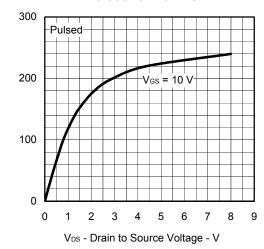


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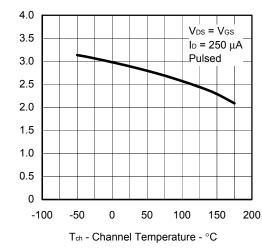
lo - Drain Current - A

Ves(th) - Gate to Source Threshold Voltage - V

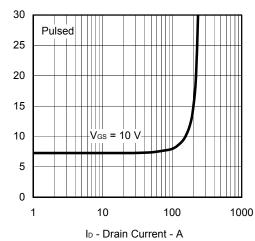
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



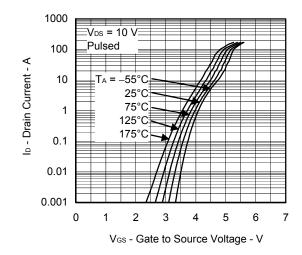
GATE TO SOURCE THRESHOLD VOLTAGE vs. CHANNEL TEMPERATURE



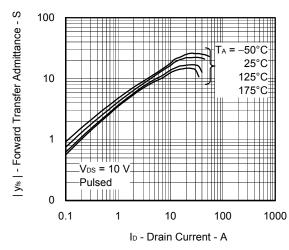
DRAIN TO SOURCE ON-STATE RESISTANCE vs. **DRAIN CURRENT**



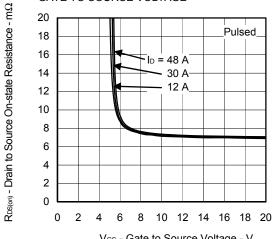
FORWARD TRANSFER CHARACTERISTICS



FORWARD TRANSFER ADMITTANCE vs. **DRAIN CURRENT**

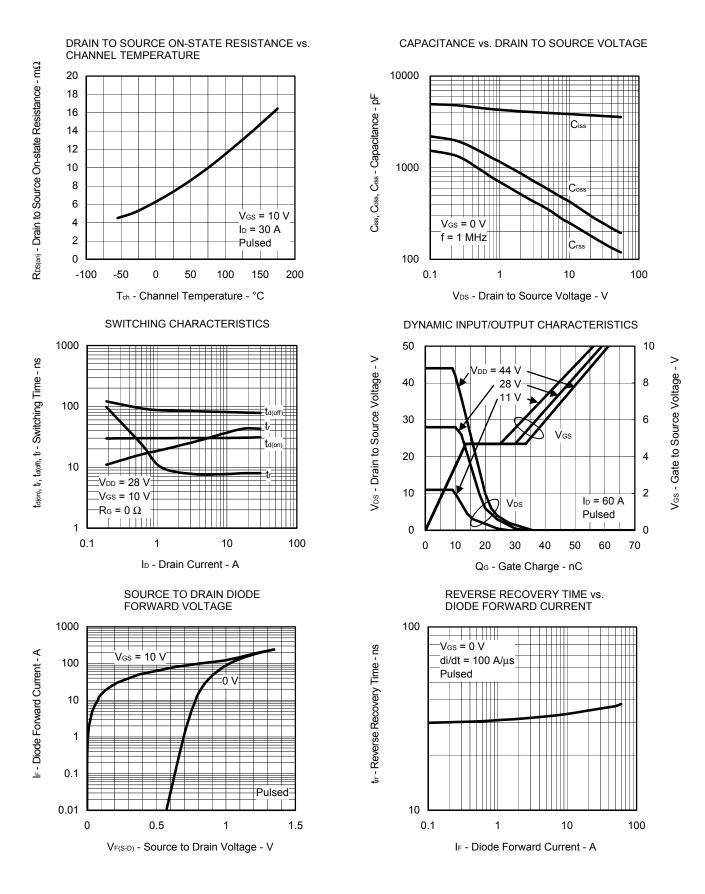


DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



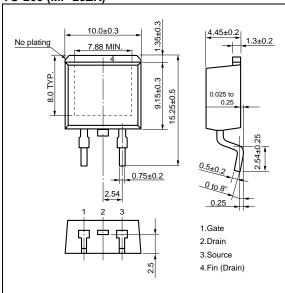
V_{GS} - Gate to Source Voltage - V

 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$ - Drain to Source On-state Resistance - $m\Omega$

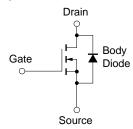


PACKAGE DRAWING (Unit: mm)

TO-263 (MP-25ZK)



EQUIVALENT CIRCUIT



Remark Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

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